Ref	Hits	Search Query	DBs	Default	Plurals	Time Stamp
#	ПІС	Search Query	DD3	Operator	riulais	. Time Stamp
S1		"048909".ap.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/09 15:26
S2	4	"2003014926"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/09 15:27
S3	2	"20030141926"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/09 15:55
S4		"565569".ap.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 14:51
S5		("20040246408" "6185032" "67625 53").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 14:57
S6	0	"JP 5-315470"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR . ,	ON	2006/11/10 14:59
S7	2	"5-315470"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11

						2005/44/42 4 4 55
S8 .	18	("5107325" "5134724" "5442223" "5459368" "5491301" "5521419" "5535101" "5564096" "5789303" "5790213" "5811882" "5814848" "5841197" "5866943" "6134428" "6144080" "6180445").PN. OR ("6396144").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 14:59
S10		"4-142163"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:12
S11	205	toshitaka.in. and nec.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/11/10 15:14
S12	9	S11 and (multilayer or "multi-layer")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:17
S13		("5155655").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:22
S14	173	(multi\$1layer near2 (package or board)) and (power near2 (terminal or electrode)) and (ground\$3 near2 (terminal or electrode)) and (insulat\$3 or dielectric) and (capacitor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 17:50
S15	199	((multi\$1layer near2 (package or board)) same (power near2 supply)) and (terminal or electrode) and (ground\$3) and (insulat\$3 or dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 17:51
S16	4794	257/300,532,535,700.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 17:46

S17	3	"05315470"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 17:50
S18	62	(multi\$1layer near2 (wiring or board)) and ((insulat\$3 or dielectric) same (power near2 supply)) and (bypass near2 capacitor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 17:57
S19	471	Tsuneoka.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:00
S20	2	S19 and (board and ground and power)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:26
S21	. 12	S19 and (ground and power)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:00
S22	. 2	"5355016".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:04
S23	45	("3614546" "4107555" "4567317" "4723156" "4909856" "5153379" "5166772").PN. OR ("5355016").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 18:17
S24	14	("5311059" "5355016" "5461545" " 5541448" "5600181" "5601675" "56 94300").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:19

S25	20	("5153379" "5168772" "5311059" " 6049469" "6388535" "6469380" "64 83175" "6487088" "6512183" "6585 149").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:26
S26	475	((printed multi\$3layer circuit) near2 (substrate or board)) and (power with ground\$3 with capacit\$4) and (ground\$3 with shield\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:42
S27	431	((printed multi\$3layer circuit) near2 (board)) and (power with ground\$3 with capacit\$4) and (ground\$3 with shield\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2006/11/10 18:38
S28	303	S26 and (power near2 (line pattern terminal electrode))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:53
S29	1447	257/691.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:53
S30	8	S29 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 18:53
S31	15	S26 and S29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 19:09
S32	242	S29 and (power near2 (line pattern conduct\$3 terminal electrode)) and ((printed circuit multi\$3layer) near2 (board or substrate)) and (insulat\$3 or dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 20:10

S33	881	(power near2 (line pattern conduct\$3 terminal electrode)) and ((printed circuit multi\$3layer) near2 (board or substrate)) and (insulat\$3 or dielectric) and ((power and ground) near plane)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 20:10
S34	20613	(PCB or ((wiring or circuit) near board)) and (coaxial or coax)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/11/14 13:57
S35	6247	S34 and (power and ground)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 13:37
S36	35	S35 and ((power and ground) with (terminal and electrode))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 13:38
S37	1081	(PCB or ((wiring or circuit) near board)) and (power with (supply plane)) and (power with (terminal or electrode)) and (ground\$3 with shield\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 13:59
S38	153	S37 and (external with power with connect\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 14:00
S39	121	S38 and (insulat\$3 or dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2006/11/14 14:02
S40	75	S39 and (power near2 (terminal or electrode))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON ·	2006/11/14 14:03

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S41	38	("20030194832" "20030197198" "20030198033" "20030202330"	US-PGPUB; USPAT;	OR	ON	2006/11/14 14:22
		"4734819" "4754366" "4853826" "5022869" "5103283"	USOCR			
		"5212402" "5272590" "5306948" "5369058" "5403195"				
		"5403784" "5438481" "5481436" 				
		"5721673 ["] ["] 5734555 ["] "5747875" "5831810" "5844419"				
			•			
		"6469895" "6489686" "6558181").PN. OR ("6885563"). URPN.				
S42	205	toshitaka.in. and nec.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM TDB	OR	ON	2006/11/14 17:33
S43 .	4800	257/300,532,535,700.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT;	OR .	ON	2006/11/14 17:33
S44	1448	257/691.ccls.	IBM_TDB US-PGPUB;	OR	ON	2006/11/14 17:34
	.=***		USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB			
S45	173	(multi\$1layer near2 (package or board)) and (power near2 (terminal or electrode)) and (ground\$3 near2 (terminal or electrode)) and (insulat\$3 or dielectric) and (capacitor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/14 17:34
S46	199	((multi\$1layer near2 (package or board)) same (power near2 supply)) and (terminal or electrode) and (ground\$3) and (insulat\$3 or dielectric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2006/11/14 17:34